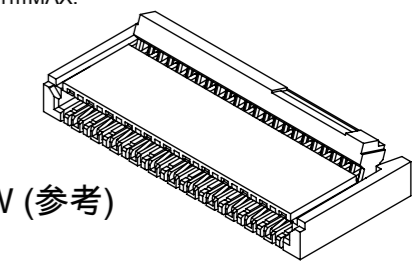


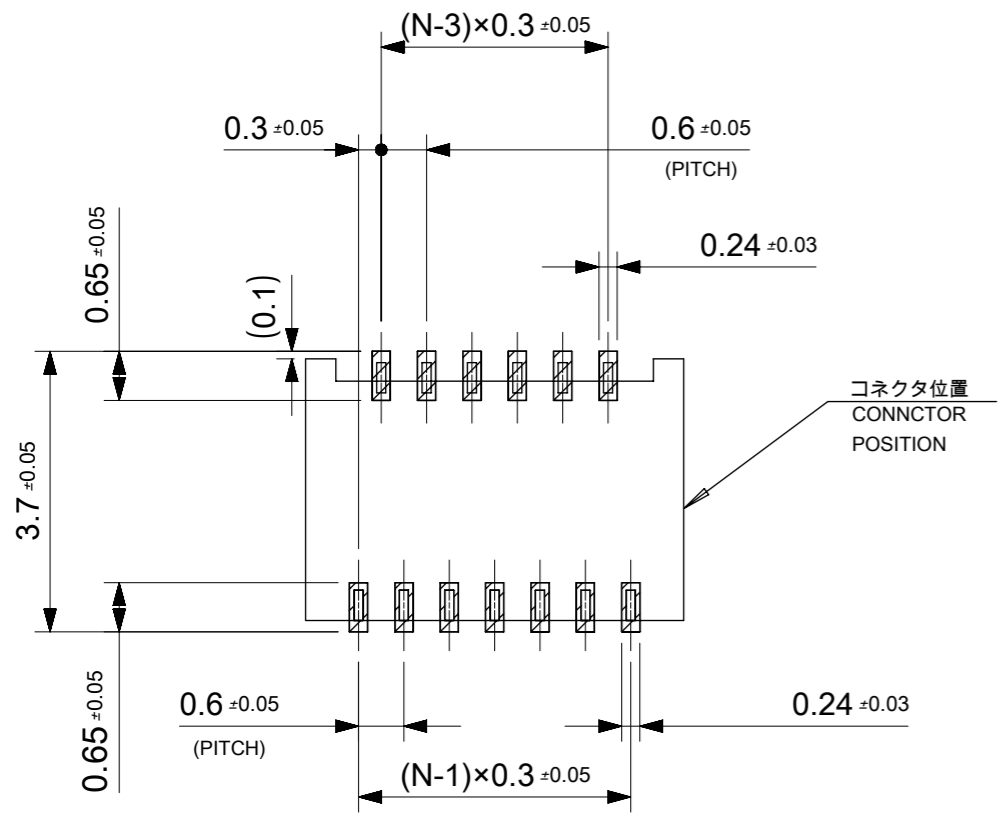
- 注記 NOTES**
1. 使用材料 MATERIALS  
 ハウジング : 液晶ポリマー(LCP)、ガラス充填、UL94 V-0、ナチュラル(白色系)  
 アクチュエータ : ポリアミド(PA)、ガラス充填、UL94、HB、黒色  
 奇数端子 : リン青銅 t=0.12mm  
 偶数端子 : リン青銅 t=0.12mm  
 HOUSING : LIQUID CRYSTAL POLYMER(LCP)、GLASS FILLED、UL94、V-0、NATURAL(WHITE)  
 ACTUATOR : POLYIMIDE(PA)、GLASS FILLED、UL94、HB、BLACK  
 ODD TERMINAL : PHOSPHOR BRONZE t=0.12mm  
 EVEN TERMINAL : PHOSPHOR BRONZE t=0.12mm
  2. メッキ仕様 PLATING  
 端子 TERMINAL  
 テール部 : 金メッキ  
 接点部 : 金メッキ 0.1μm以上  
 下地 : ニッケルメッキ 1.0μm以上  
 TAIL AREA: Gold PLATING  
 CONTACT AREA: Gold PLATING 0.1μm MINIMUM  
 UNDER PLATING: Nickel PLATING 1.0μm MINIMUM
  3. 端子の平坦度は0.1mm以下とする  
 COPLANALITY OF SOLDER TAILS: 0.1mm MAX.
  4. ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT



18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.8	6.6	7.2	8.6	504740-2500	25
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
3.6	2.4	3.0	4.4	504740-1100	11
D	C	B	A	EMBOSSED TAPE	CIRCUITS
				ORDER NO. オーダー番号	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

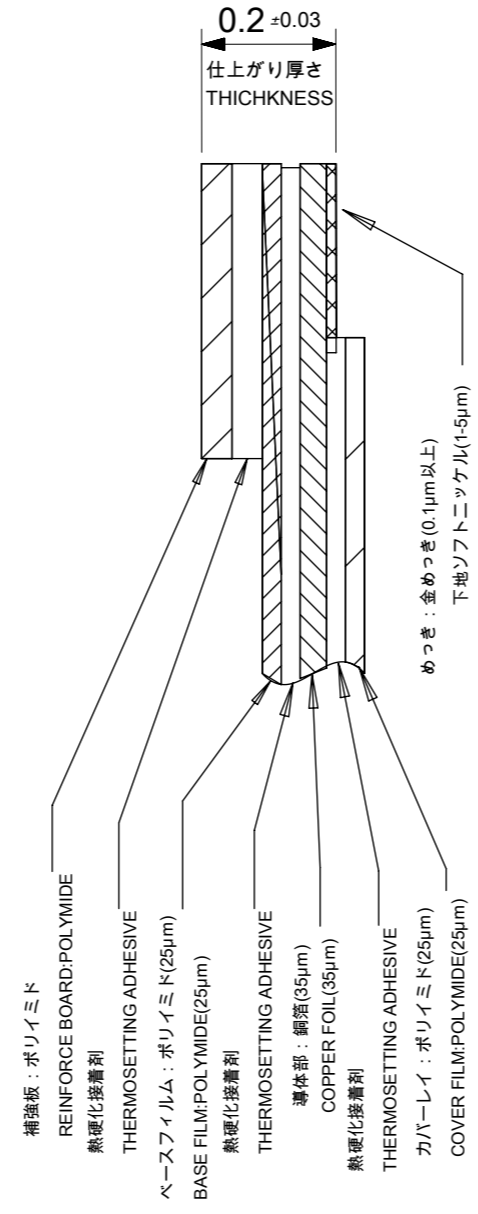
EC NO: 116601 DRWN: TYAMANE CHK'D: YKOBAYASHI02 APPR: TKUSUHARA01	2017/05/08 2017/05/08 2017/05/08	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 1.0 ° 4 PLACES ± 0.03 3 PLACES ± 0.03 2 PLACES ± 0.05 1 PLACE ± 0.1 0 PLACES ± 0.2	DIMENSION UNITS: MM SCALE: —		
	DRWN BY: SHIRATA CHK'D BY: KTAKAHASHI APPR BY: KMORIKAWA	DATE: 2015/03/03 DATE: 2015/05/22 DATE: 2016/08/02	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWING SIZE: A3 THIRD ANGLE PROJECTION
	PRODUCT CUSTOMER DRAWING				SERIES: 504740 MATERIAL NUMBER: SEE CHART CUSTOMER: GENERAL
	ORDER NO. 5047401000		DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 1 OF 2		



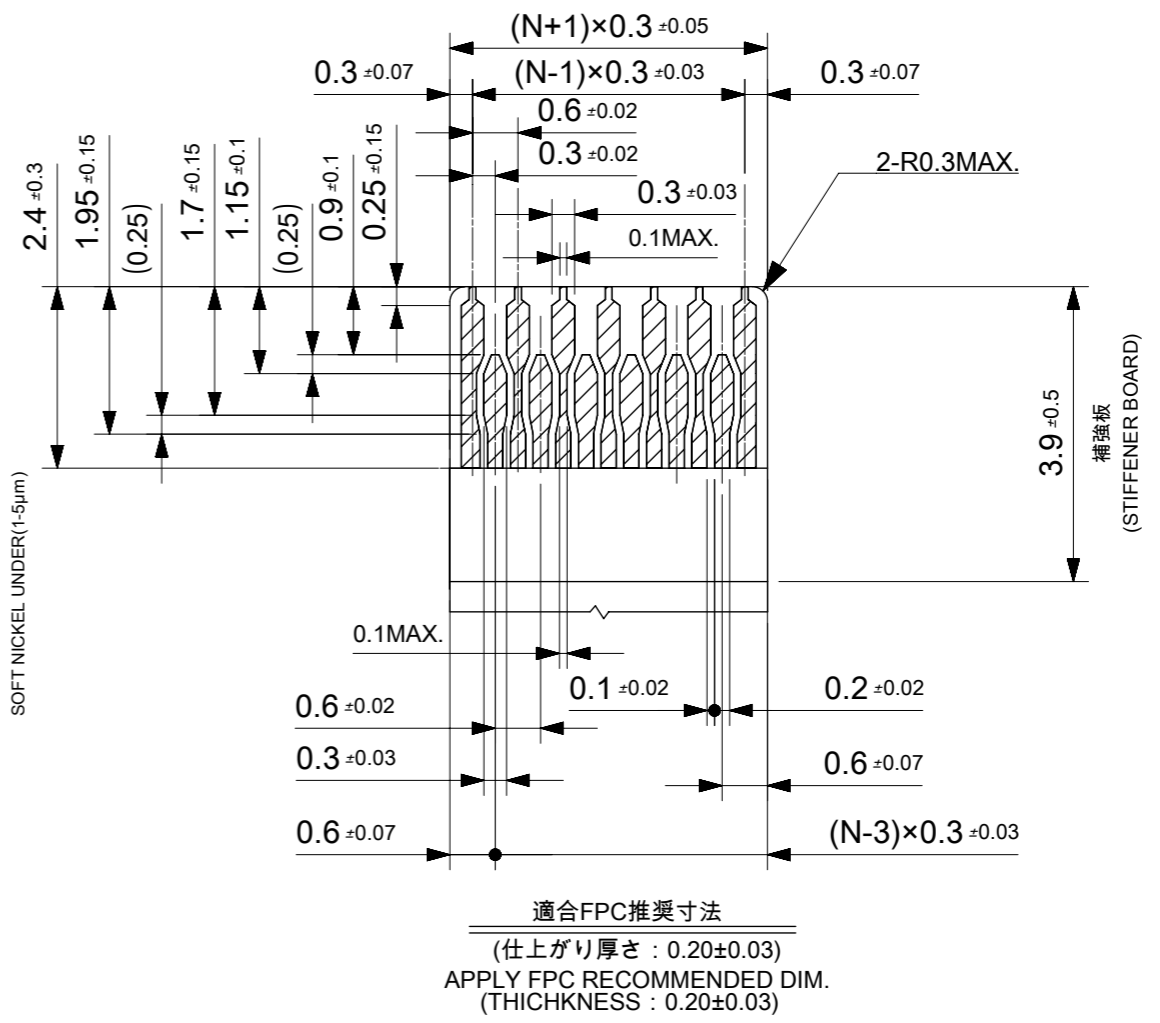
参照基板レイアウト(マウント面)  
P.W. BOARD PATTERN  
DIM.(REF)

推奨メタルマスク厚さ : 0.1mm  
RECOMMENDED METAL MASK THICKNESS : 0.1mm

推奨開口率 : 80%  
APERTURE RATE : 80%



FPC構成推奨仕様  
STRUCTURE OF FPC



FPCについて (ABOUT FPC)  
抜き方向は、導体側から補強版側を推奨致します。  
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
RECOMMENDED PUNCHER DIRECTION:  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL:  
STIFFENER BOARD: POLYIMIDE  
BONDING AGENT: THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND  
BECAUSE THERE IS A POSSIBILITY THAT  
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。  
WHEN STIFFNER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFNER BOARD AS 0.5mm MINIMUM.

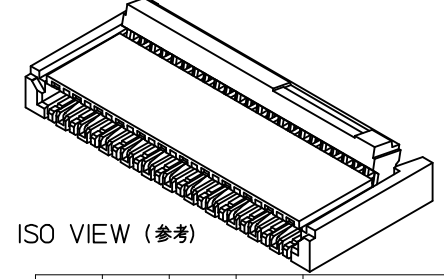
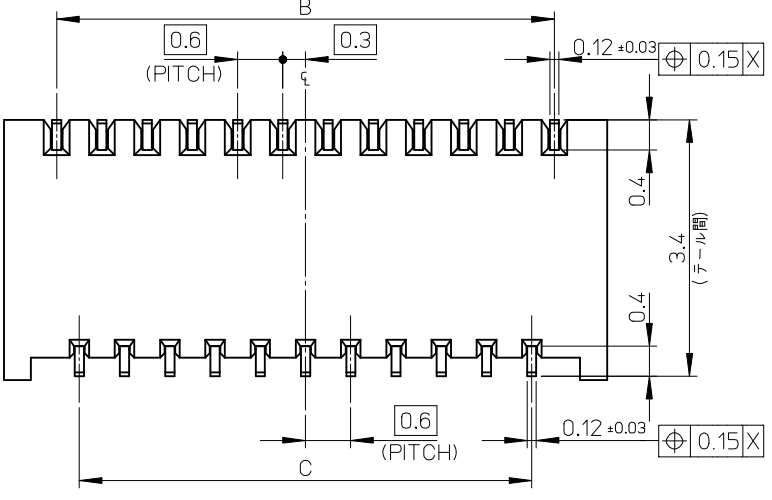
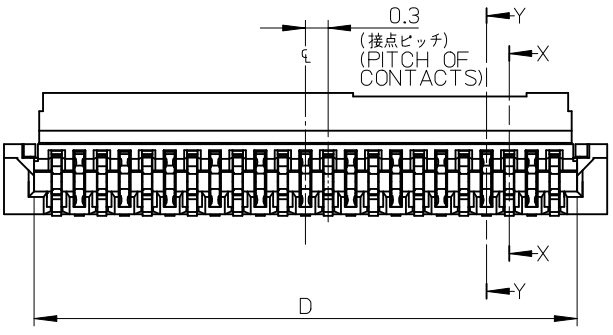
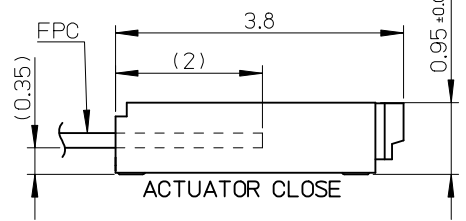
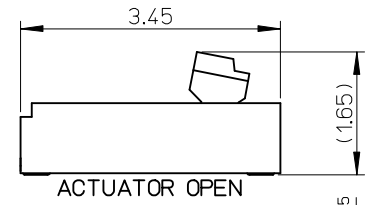
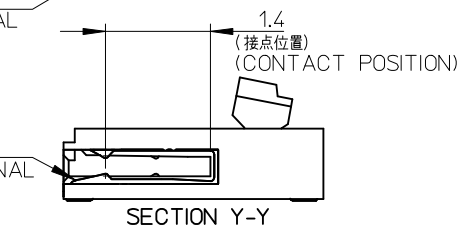
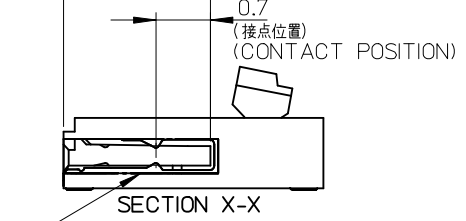
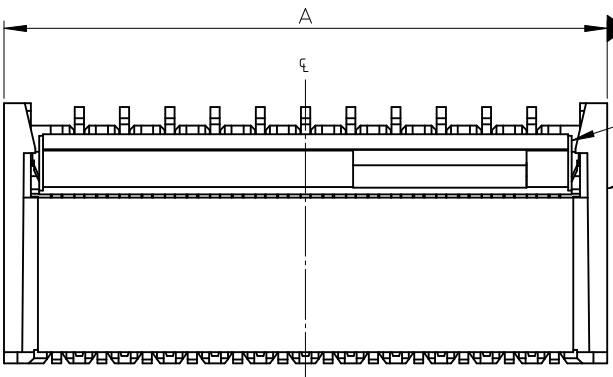
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Rev H 2014/11/25

RELEASE STATUS	P1	RELEASE DATE	08.05.2017	09:12:54
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THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
EC NO: 116601 DRWN: TYAMANE CHK'D: YKOBAYASHI02 APPR: TKUSUHARA01	2017/05/08	2017/05/08	2017/05/08	GENERAL TOLERANCES (UNLESS SPECIFIED)			
	4 PLACES	± 0.03					
	3 PLACES	± 0.03					
	2 PLACES	± 0.05					
	1 PLACE	± 0.1					
	0 PLACES	± 0.2					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							
DIMENSION UNITS		SCALE		molex®			
MM		---					
DRWN BY		DATE		0.3 FPC CONN. BF H=0.95 HOUSING ASSY			
SHIRATA		2015/03/03					
CHK'D BY		DATE					
KTAKAHASHI		2015/05/22		PRODUCT CUSTOMER DRAWING			
APPR BY		DATE					
KMORIKAWA		2016/08/02		SERIES	MATERIAL NUMBER	CUSTOMER	
DRAWING SIZE		THIRD ANGLE PROJECTION		504740	SEE CHART	GENERAL	
A3		[Symbol]		DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
B		REV		5047401000	PSD	000	2 OF 2

注記 NOTES

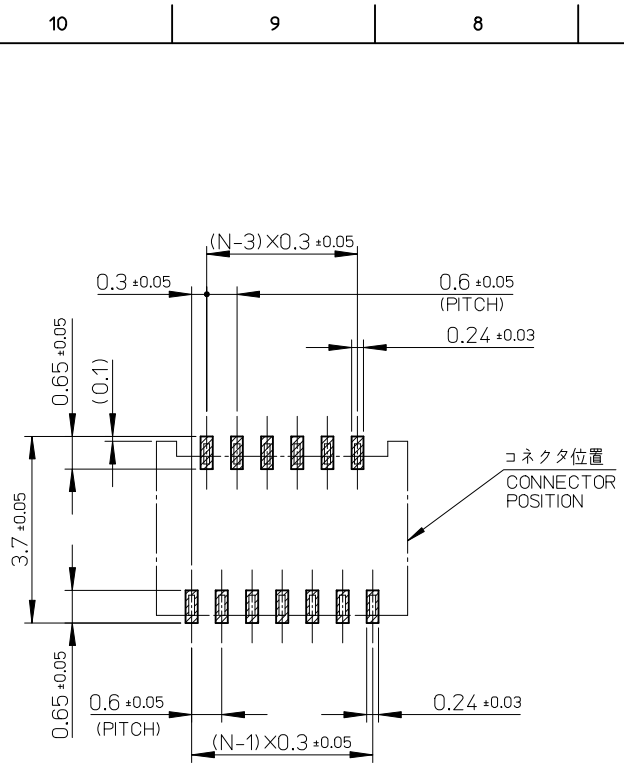
- 使用材料 MATERIALS  
 ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94 V-0、ナチュラル (白色系)  
 アクチュエータ: ポリアミド (PA)、ガラス充填、UL94 HB、黒色  
 奇数端子 : リン青銅 t=0.12mm  
 偶数端子 : リン青銅 t=0.12mm  
 HOUSING : LIQUID CRYSTAL POLYMER (LCP)、GLASS FILLED、UL94 V-0、NATURAL (WHITE)  
 ACTUATOR : POLYAMIDE (PA)、GLASS FILLED、UL94 HB、BLACK  
 ODD TERMINAL : PHOSPHOR BRONZE t=0.12mm  
 EVEN TERMINAL : PHOSPHOR BRONZE t=0.12mm
- メッキ仕様 PLATING  
 端子 TERMINAL  
 テール部: 金メッキ  
 接点部: 金メッキ 0.1μm以上  
 下地: ニッケルメッキ 1.0μm以上  
 TAIL AREA : Gold PLATING  
 CONTACT AREA : Gold PLATING 0.1μm MINIMUM  
 UNDER PLATING : Nickel PLATING 1.0μm MINIMUM
- 端子の平坦度は0.1mm以下とする  
 COPLANALITY OF SOLDER TAILS: 0.1mmMAX.
- ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT



18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
D	C	B	A	EMBOSSED TAPE	CIRCUITS
				ORDER NO. オーダー番号	

CONNECTOR SERIES NO. 504740-\*\*-09

REVISED EC NO: J2015-1144 DR: M. N. SANUMA 2015/03/06 CHK: K. TAKAHASHI 2015/04/13 APPR: Y. NOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER 10 UNDER	±0.2	HIJIMA	2013/07/17			
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.	
30 OVER	±0.3	YNOGAWA	2014/03/05	SD-504740-001		1 OF 2	
ANGULAR	±1 °	MATERIAL NO.		SEE CHART			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参照基板レイアウト(マウント面)

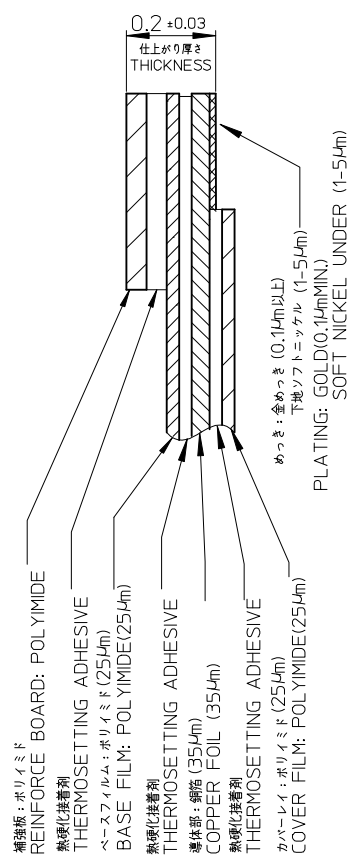
P.W. BOARD PATTERN  
DIM.(REF)

推奨メタルマスク厚さ : 0.1mm

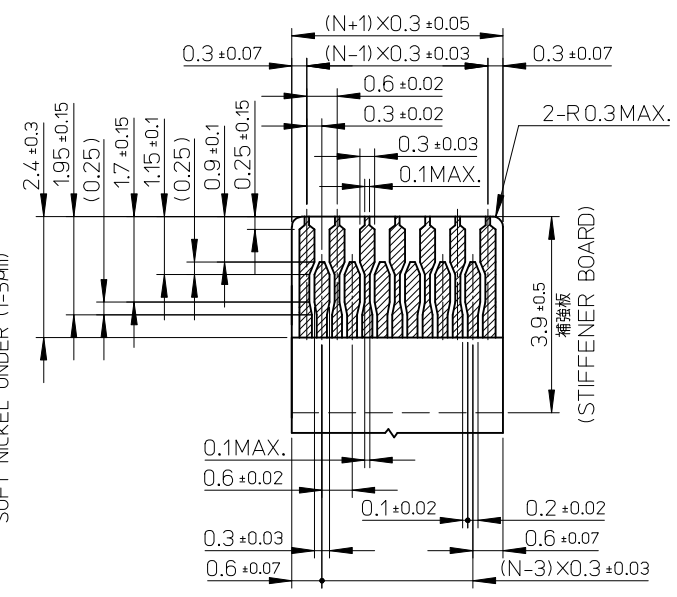
RECOMMENDED METAL MASK THICKNESS : 0.1mm

推奨開口率 : 80%

APERTURE RATE : 80%



FPC構成推奨仕様  
STRUCTURE OF FPC



適合FPC推奨寸法

(仕上がり厚さ : 0.20±0.03)

APPLY FPC RECOMMENDED DIM.  
(THICKNESS : 0.20±0.03)

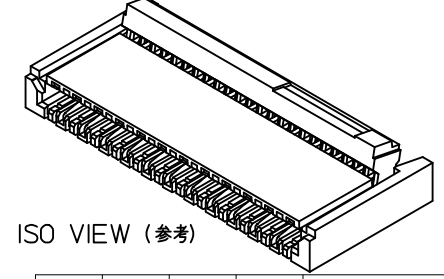
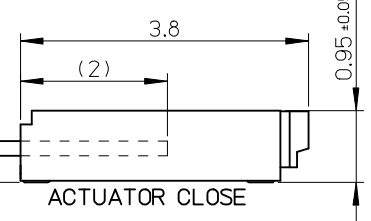
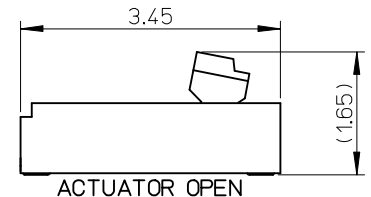
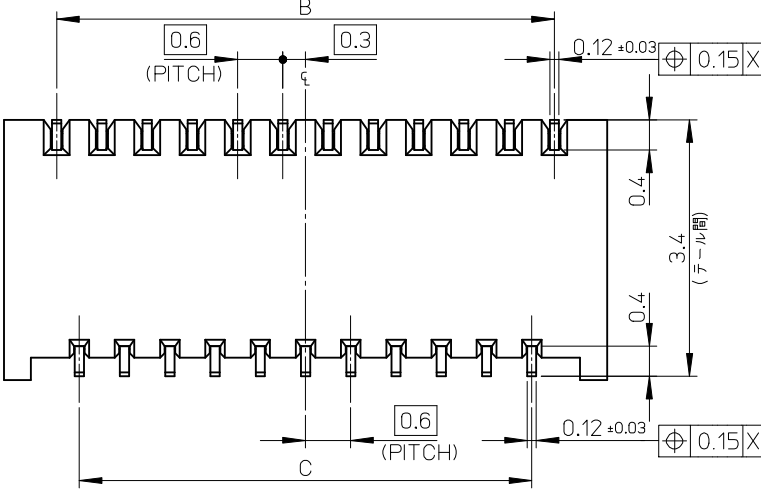
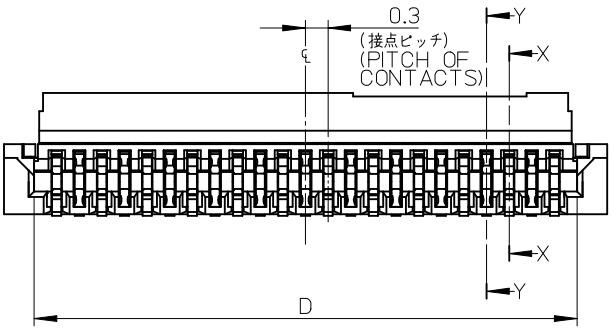
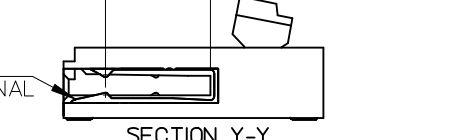
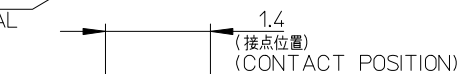
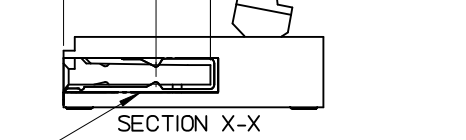
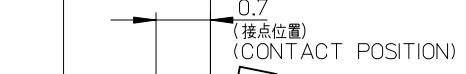
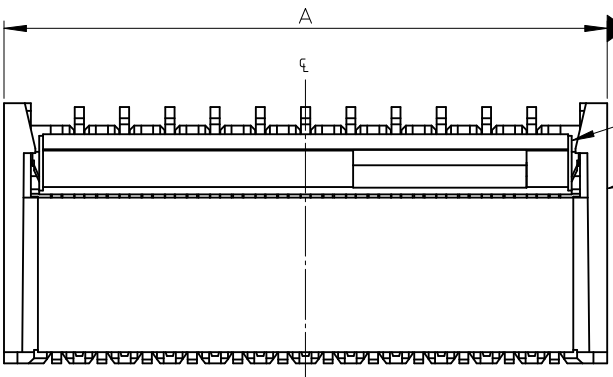
FPCについて (ABOUT FPC)  
 抜き方向は、導体側から補強版側を推奨致します。  
 補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨致します。  
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
 RECOMMENDED PUNCHER DIRECTION:  
 FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL:  
 STIFFENER BOARD: POLYIMIDE  
 BONDING AGENT: THERMOSETTING AGENT  
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND  
 BECAUSE THERE IS A POSSIBILITY THAT  
 THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。  
 WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

SEE SHEET 1 OF 2 EC NO: J2015-1144 DRAWN: SANUMA 2015/03/06 CHKD: TAKAHASHI 2015/04/13 APPR: YNOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
1.0 OVER 10 UNDER	±0.2	HIJIMA	2013/07/17				
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.			
30 OVER	±0.3	YNOGAWA	2014/03/05	SD-504740-001			
ANGULAR ±1 °		MATERIAL NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE SHEET 1 OF 2	2 OF 2			
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記 NOTES

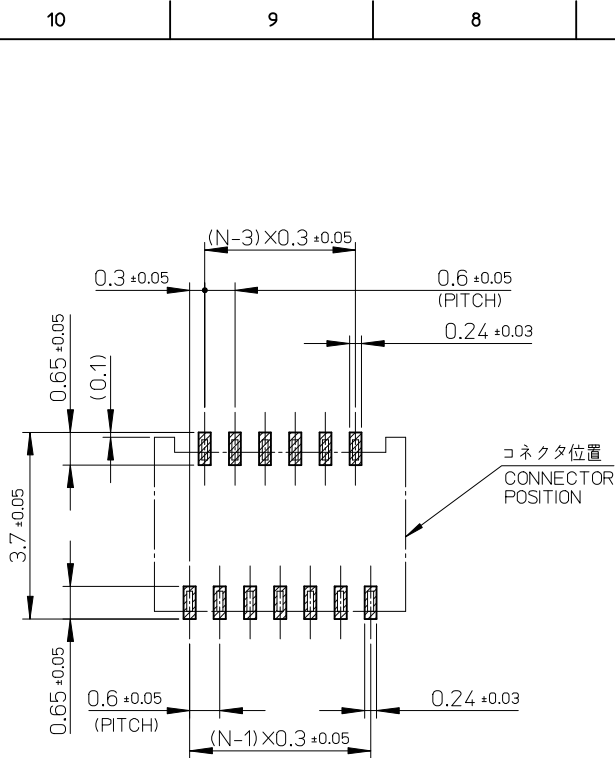
- 使用材料 MATERIALS  
 ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94 V-0、ナチュラル (白色系)  
 アクチュエータ: ポリアミド (PA)、ガラス充填、UL94 HB、黒色  
 奇数端子 : リン青銅 t=0.12mm  
 偶数端子 : リン青銅 t=0.12mm  
 HOUSING : LIQUID CRYSTAL POLYMER (LCP)、GLASS FILLED、UL94 V-0、NATURAL (WHITE)  
 ACTUATOR : POLYAMIDE (PA)、GLASS FILLED、UL94 HB、BLACK  
 ODD TERMINAL : PHOSPHOR BRONZE t=0.12mm  
 EVEN TERMINAL : PHOSPHOR BRONZE t=0.12mm
- メッキ仕様 PLATING  
 端子 TERMINAL  
 テール部: 金メッキ  
 接点部: 金メッキ 0.1μm以上  
 下地: ニッケルメッキ 1.0μm以上  
 TAIL AREA : Gold PLATING  
 CONTACT AREA : Gold PLATING 0.1μm MINIMUM  
 UNDER PLATING : Nickel PLATING 1.0μm MINIMUM
- 端子の平坦度は0.1mm以下とする  
 COPLANALITY OF SOLDER TAILS: 0.1mmMAX.
- ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT



18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
D	C	B	A	EMBOSSED TAPE	CIRCUITS
ORDER NO. オーダー番号					

CONNECTOR SERIES NO. 504740-\*\*-09

REVISED EC NO: J2015-1144 DR: M. N. SANUMA 2015/03/06 CHK: K. TAKAHASHI 2015/04/13 APPR: Y. NOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER 10 UNDER	±0.2	HIJIMA	2013/07/17			
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.			
30 OVER	±0.3	YNOGAWA	2014/03/05	SD-504740-001			
ANGULAR	±1 °	MATERIAL NO.	SEE CHART		SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参照基板レイアウト(マウント面)

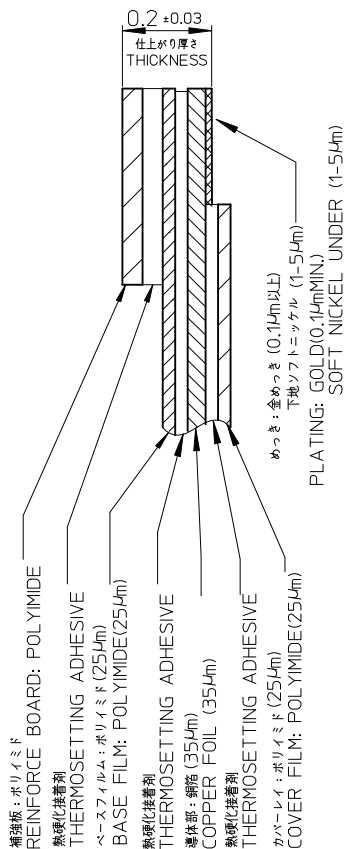
P.W. BOARD PATTERN  
DIM.(REF)

推奨メタルマスク厚さ : 0.1mm

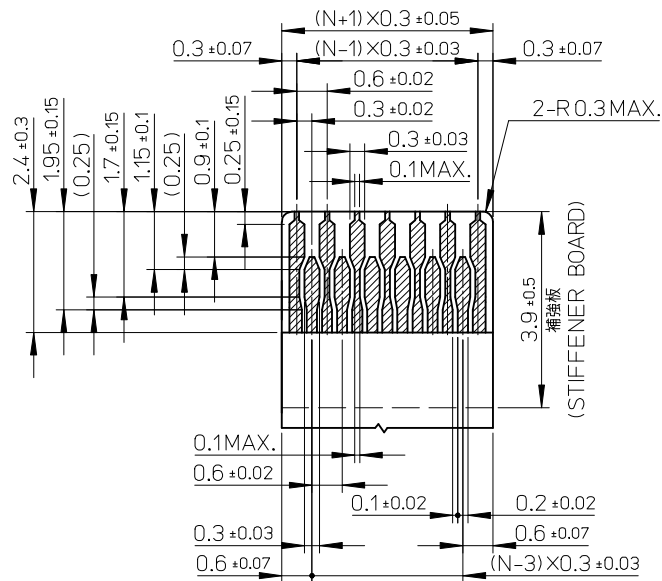
RECOMMENDED METAL MASK THICKNESS : 0.1mm

推奨開口率 : 80%

APERTURE RATE : 80%



FPC構成推奨仕様  
STRUCTURE OF FPC



適合FPC推奨寸法

(仕上がり厚さ : 0.20 ± 0.03)

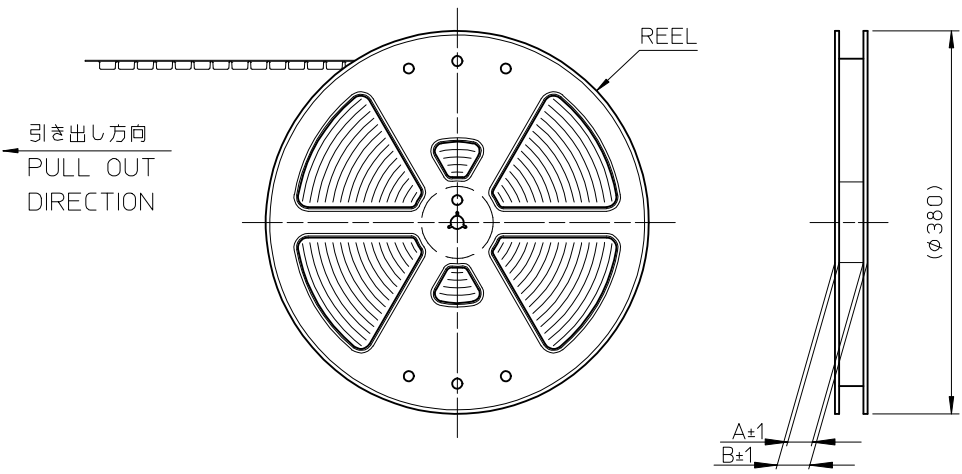
APPLY FPC RECOMMENDED DIM.  
(THICKNESS : 0.20 ± 0.03)

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強版側を推奨致します。  
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
RECOMMENDED PUNCHER DIRECTION:  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL:  
STIFFENER BOARD: POLYIMIDE  
BONDING AGENT: THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND  
BECAUSE THERE IS A POSSIBILITY THAT  
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

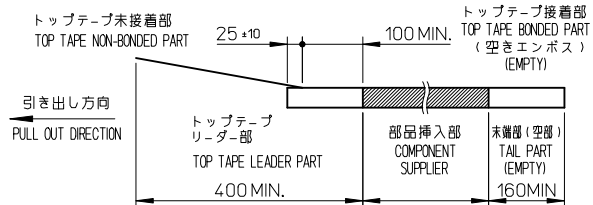
※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。  
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY			METRIC		
0.25	UNDER			±0.03	DRAWN BY	DATE	TITLE		
0.25	OVER	0.5	UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY <b>molex</b>		
0.5	OVER	1.0	UNDER	±0.1	CHECKED BY	DATE			
1.0	OVER	10	UNDER	±0.2	HIJIMA	2013/07/17			
10	OVER	30	UNDER	±0.25	APPROVED BY	DATE			
30	OVER			±0.3	YNOGAWA	2014/03/05			
ANGULAR				±1 °	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
SEE SHEET 1 OF 2				SEE SHEET 1 OF 2		SD-504740-001		2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



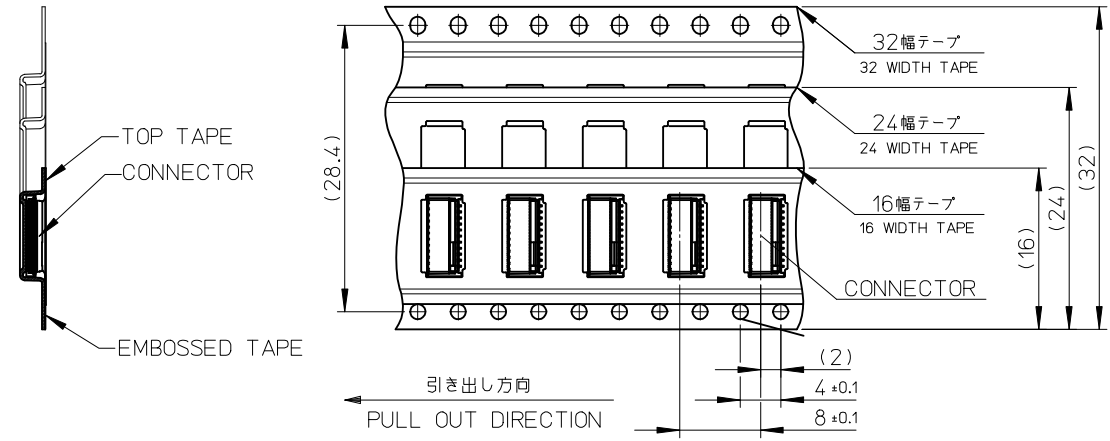
**NOTES**

- 製品詳細寸法については、図面 SD-504740-001をご参照下さい。  
REFER TO THE SD-504740-001 ABOUT DIMENSIONS IN DETAIL.
- 梱包数量 : 5000 個/リール  
NUMBER OF CONNECTORS : 5000 PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- トップテープの剥離強度については、IEC60286-3 に準拠  
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

5. 材料  
 キャリアテープ : ポリスチレン (PS)  
 トップテープ : PET, OTHER  
 リール : ポリスチレン (PS) <リサイクル材を含む>  
**MATERIAL**  
 CARRIER TAPE : POLYSTYRENE(PS)  
 TOP TAPE : PET, OTHER  
 REEL : POLYSTYRENE(PS)  
 <RECYCLE MATERIAL CONTAINED>



32	37.4	33.4	504740-6100	61
			504740-5100	51
24	29.4	25.4	504740-4500	45
			504740-4100	41
			504740-3900	39
			504740-3700	37
			504740-3300	33
16	21.4	17.4	504740-2300	23
			504740-1900	19
テープ幅 TAPE WIDTH	B	A	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	CIRCUIT
CONNECTOR SERIES NO.			504740-**-09	

エンボステープ内の製品の向き  
 DIRECTION OF CONNECTOR IN  
 EMBOSSSED TAPE

REVISED EC NO: J2015-1144 DRWN:NASUNUMA 2015/03/06 CHKD:KAKAHASHI 2015/04/13 APPR:YNOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 4:0	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY TONO	DATE 2013/07/25	TITLE 0.3 FPC CONN. BACK FLIP HGT=0.95MM EMBSTP PKG		
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY HIIJIMA	DATE 2013/07/25			
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY YNOGAWA	DATE 2014/03/05			
	1.0 OVER	30 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	SEE CHART SD-504740-002 1 OF 1	
10 OVER	30 UNDER	±0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		